



#22/E (NE)

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2/4/03

Smith
2/25/13

Smith

In re Application of:

Salman Akram

Serial No.: 09/388,031

Filed: September 1, 19999

For: METALLIZATION STRUCTURES
FOR SEMICONDUCTOR DEVICE
INTERCONNECTS, METHODS FOR
MAKING SAME, AND
SEMICONDUCTOR DEVICES
INCLUDING SAME

Confirmation No.: 3303

Examiner: E. Lee

Group Art Unit: 2815

02/04/2003 ASMITH 00000008 201469 09388031

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Attorney Docket No.: 3442.2US (96-428)

CERTIFICATE OF MAILING

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December 26, 2002
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Joseph A. Walkowski

Typed/printed name of person whose signature is contained above

AMENDMENT UNDER 37 C.F.R. §1.116

Box AF
Commissioner for Patents
Washington, D.C. 20231

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed September 25, 2002, the three-month shortened statutory period for response to which expires on December 25, 2002. This response is submitted on or before three months from the mailing date of the Final Office Action, December 25, 2002 being a holiday.

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